

Specifications

<i>Technology</i>	Stepper motor driven Y and Z axes Single board PC controller, menu programming BPC 2000 on-line bond process control unit (optional)
<i>Wire Types</i>	20 to 75 µm diameter gold & aluminium wire on 2" spool, ribbon from 30 to 250 µm on 2" mechanical spool
<i>Bond Head</i>	90° wire feed Electronic touchdown sensing for every bond Programmable output ultrasonic system, 0 to 5W, 60 kHz or 100 kHz; Optionally: 140 kHz Programmable bond force 15 to 150 cN Conversion kits for fine wire ball and/or heavy wire wedge bonding available
<i>Working Area</i>	Y axis: 50 mm, Z axis: 50 mm, 2.5 µm resolution Standard work height 136 mm (mid Z stroke) X/Y manipulator from 5 x 5 mm to 18 x 18 mm Equivalent manipulator step-down 1:2 to 1:7
<i>Work Holder</i>	Standard 60 mm Ø for parts up to 2" x 2", mechanical clamping Optionally 4" x 4", mechanical and vacuum clamping Heated work holder with digitally programmed temperature control up to 360°C
<i>Operating Modes</i>	Manual, semi-automatic, automatic, multi-wire Step mode for programme debug
<i>Loops</i>	Standard rectangular, standard triangular, single reverse, double reverse stitch; table tear
<i>Programme Storage</i>	Up to 50 individual wires per programme, 250 programmes per 3.5" floppy disk, can be edited and printed as text files via PC
<i>Dimensions</i>	Height 50 cm, width 60 cm, depth 60 cm, Weight approx. 55 kg
<i>Supplies</i>	100 - 230 V, single phase; air pressure and vacuum 6 mm Ø connector if necessary



5432

Deep Access
Manual and Semi-
automatic Bonder for
Wire and Ribbon

The user programmable model 5432 wedge-wedge bonder can process gold and aluminium wires from 20 to 75 µm diameter and ribbon from 30 to 250 µm width. For wire diameters under 25 µm and for all ribbons a motor driven wire feed option is available. The compact desk top machine is ideal for laboratory, prototyping and repair applications. The stepping motor driven Y and Z axes enable single or multiple bonds to be executed reliable and repeatable under full programme control. Operators require only a minimum of training making the 5432 the ideal choice for pre-series and small scale production lines.

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